Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

BOARD CHARACTERISTICS

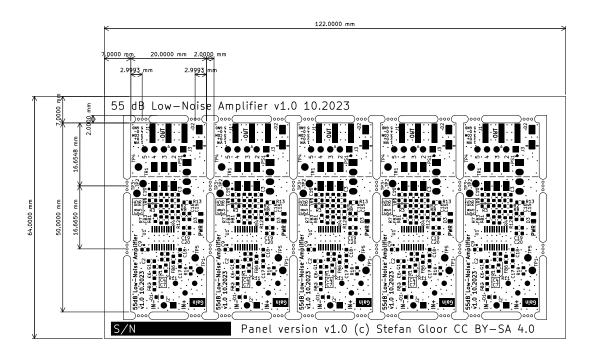
Copper Layer Count: Board Thickness: 1.6000 mm

Board overall dimensions: 122.0000 mm x 64.0000 mm

Min track/spacing: 0.1500 mm / 0.1500 mm Min hole diameter: 0.3000 mm

Copper Finish: None Impedance Control: No Castellated pads: Νo Plated Board Edge: No

Edge card connectors: Νo



File: current_probe.kicad_pcb

Title: Low-Noise Amplifier Current Probe

Size: A4 Date: 2023-10-07 Rev: KiCad E.D.A. kicad 7.0.1 ld: 1/1